

Bill of Materials

TI DESIGNS
TIPD157: Single Supply Unipolar MDAC

Item #	Quantity	Designator	Value	Description	Manufacturer	Manufacturer Part Number 1	Supplier Part Number 1
1	1	J2		Header, TH, 100mil, 4x2, Gold plated, 230 mil above insulator	Samtec	TSW-104-07-G-D	SAM1028-04-ND
2	2	R2, R3	10.0k	RES, 10.0k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-103-B-T5	RG16P10.0KBCT-ND
3	1	U3		Low-Noise, Very Low Drift, Precision Voltage Reference, D0008A	Texas Instruments	REF5050ID	296-22212-5-ND
4	1	U2		Low-Noise, Low Quiescent Current, Precision Operational Amplifier e-trim™ Series, PW0014A	Texas Instruments	OPA4376AIPW	296-26288-5-ND
5	3	C6, C7, C9	0.1uF	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	MuRata	GRM188R71E104KA01D	490-1524-1-ND
6	1	J1		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS	ED1514-ND
7	1	J3		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS	ED1514-ND
8	1	U1		12-Bit, Serial Input, Multiplying Digital-to-Analog Converter, DGS0010A	Texas Instruments	DAC7811IDGS	296-33261-5-ND
9	1	R1	1.5 ohm	RES, 1.50 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW06031R50FKEA	541-1.50HHCT-ND
10	1	C5	47uF	CAP, CERM, 47uF, 25V, +/-20%, X5R, 1206	TDK	C3216X5R1E476M160AC	445-8047-1-ND
11	1	C1	10uF	CAP, CERM, 10uF, 25V, +/-10%, X5R, 0805	TDK	C2012X5R1E106K125AB	445-5984-1-ND
12	3	C2, C3, C4	1uF, 0.1uF, 1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603, CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603, CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	Kemet, MuRata, Kemet	C0603C105K4PACTU, GRM188R71E104KA01D, C0603C105K4PACTU	399-5090-1-ND, 490-1524-1-ND, 399-5090-1-ND
13	2	C8, C10	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	Kemet	C0603C105K4PACTU	399-5090-1-ND
14	1	TP1	Red	Test Point, Miniature, Red, TH	Keystone	5000	5000K-ND
15	1	TP2	Red	Test Point, Miniature, Red, TH	Keystone	5000	5000K-ND
16	2	TP3, TP4	Red	Test Point, Miniature, Red, TH	Keystone	5000	5000K-ND
17	3	FID1, FID2, FID3		Fiducial mark. There is nothing to buy or mount.	N/A		

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